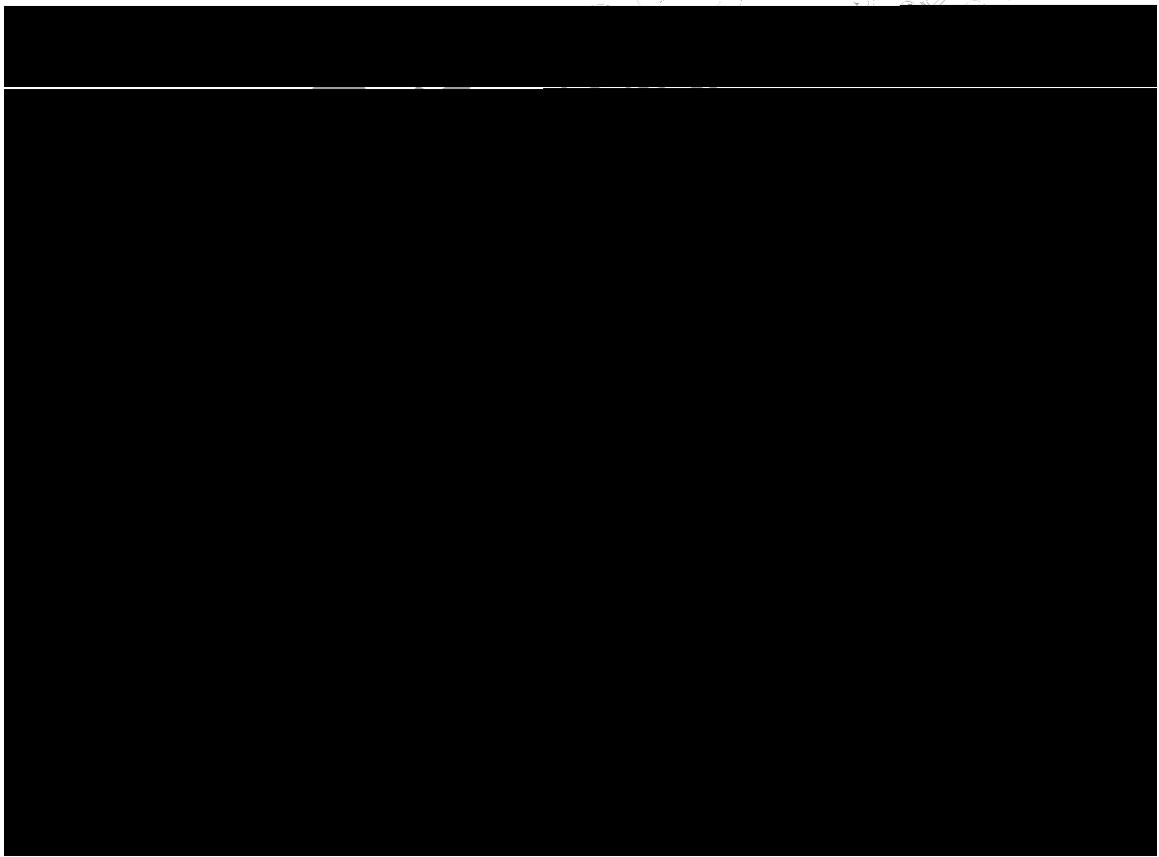




TABLE OF CONTENTS

Applications	Application Circuits
Absolute Maximum Ratings	Application Note
Electrical Characteristics	Application Note
Pin Configuration and Pin Descriptions	Boost Converter
Timing Characteristics	ET
Typical Applications	Control Loop Considerations
Low Frequency Driver	High Frequency Drivers
High Frequency Driver	



PECIFICA ION





 C n' s s o r w' s n o
 ab e

	●	● on l on	n	n t
PWM INPUT				
Input Voltage High ²			2.0	V
Input Voltage Low ²			0.8	V
Input Current ²			-1	+1
Hysteresis ²			90	250
OD INPUT				
Input Voltage High ²			2.0	V
Input Voltage Low ²			0.8	V
Input Current ²			-1	+1
Hysteresis ²			90	250
Propagation Delay Times ³	tpd_{OD}	See Figure 3	20	35
	tpd_{OD}	See Figure 3	40	55
HIGH-SIDE DRIVER				
Output Resistance, Sourcing Current		BST to SW = 12 V	3.8	4.4
Output				1.8
Output				k
Transit				55
				45
Propag				65
				35
SW Pul				k
LOW-SIDE				
Output				4.0
Output				1.8
Output				k
Transit				50
				30
Propag				35
				40
Time-o				ns
				ns
SUPPLY				
Supply				13.2
Supply				5
UVLO V				3.0
Hyster				mV

1

ADP

ABOL E MAXIM M RA ING

ab e

Parameter	Value
VCC	-0.3 V to +15 V
BST	-0.3 V to VCC + 15 V
BST to SW	-0.3 V to +15 V
SW	
DC	-5 V to +15 V
<200 ns	-10 V to +25 V
DRVH	
DC	SW - 0.3 V to BST + 0.3 V
<200 ns	SW - 2 V to BST + 0.3 V
DRVL	
DC	-0.3 V to VCC + 0.3 V
<200 ns	-2 V to VCC + 0.3 V
IN, OD	-0.3 V to 6.5 V
J _A , SOIC_N	
2-Layer Board	123°C/W
4-Layer Board	90°C/W
Operating Ambient Temperature Range	0°C to 95°C
Junction Temperature	
Storage Temperature	
Lead Temperature	
Soldering Temperature	
Vapor Phase Reflow Temperature	
Infrared Reflow Temperature	

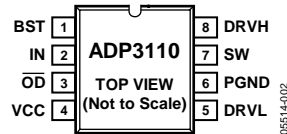
r ss s... os is n rA... ings
 by c s pr n n g o ic T is s s r ss
 ring on y nc on op r on o ic s or ny
 o r con ions no os in ic in op r on
 s c on o is sp c on s no i p E pos r o so
 ring con ions or n p ro s y c
 ic r y n' sso r w is sp c o r o g s
 r r nc o D



A
 ESD (electrostatic discharge) protection is provided for the human body, proprietary information, and electrostatic degradation.



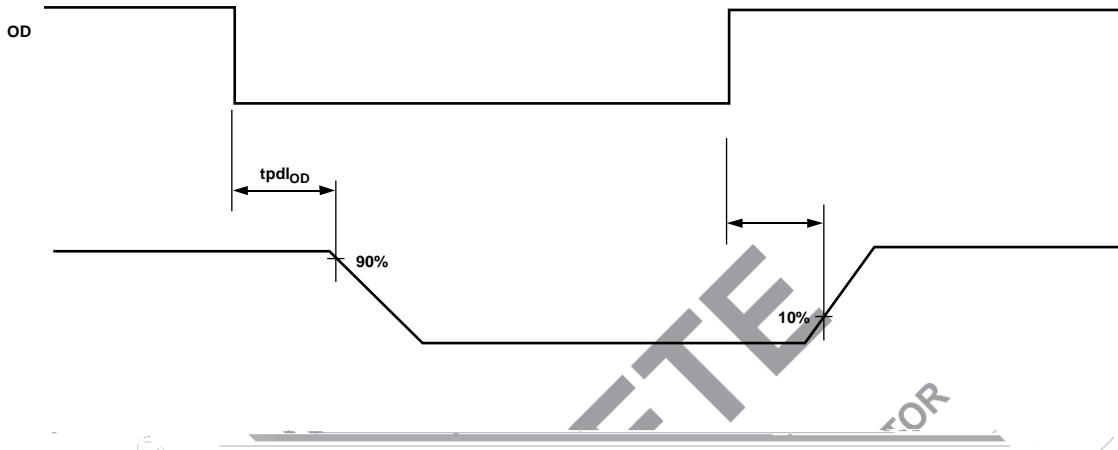
PIN CONFIGURATION AND FUNCTION DESCRIPTION



For more information, see the ADP3110 datasheet.

Pin	Symbol	Function Description
1	BST	Upper MOSFET Floating Bootstrap Supply. A capacitor connected between the BST and SW pins holds this bootstrapped voltage for the high-side MOSFET as it is switched.
2	IN	Logic Level PWM Input. This pin has primary control of the driver outputs. In normal operation, pulling this pin low turns on the low-side driver; pulling it high turns on the high-side driver.
3	OD	

TIMING CHARACTERISTICS



T ET n ors o / pro i o g s w
r r n c r r n r i n g s c s c n sign
ro n T n s p s o r i n p c
c r r n i n ET T s c n on by



0 LINE DIMENSION



0.25 (0.0098) 1.27 (0.0500)
0.17 (0.0067) 0.40 (0.0157)

